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BSS138-F085

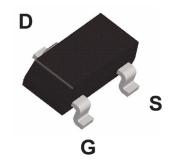
N-Channel Logic Level Enhancement Mode Field Effect Transistor

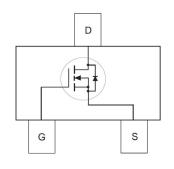
General Description

These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- · Automotive Qualified
- 0.22 A, 50 V. RDS(ON) = 3.5Ω @ VGS = 10 V $RDS(ON) = 6.0\Omega$ @ VGS = 4.5 V
- High density cell design for extremely low RDS(ON)
- · Rugged and Reliable
- · Compact industry standard SOT-23 surface mount package





Absolute Maximum Rations

SOT-23

T_A = 25°C unless otherwise noted

| Symbol | Parameter | Units | Symbol |
|-----------------------------------|---|-------------|--------|
| V _{DSS} | Drain-Source Voltage | 50 | V |
| V _{GSS} | Gate-Source Voltage | ±20 | V |
| 1 | Drain Current – Continuous (Note | 1) 0.22 | |
| ıD | - Pulsed | 0.88 | A |
| D | Maximum Power Dissipation (Note | 0.36 | W |
| P_{D} | Derate Above 25°C | 2.8 | mW/°C |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | -55 to +150 | °C |
| TL | Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds | 300 | °C |

Thermal Characteristics

| R _{θJA} Thermal Resistance, Junction-to-Ambient | (Note 1) | 350 | °C/W |
|--|----------|-----|------|
|--|----------|-----|------|

Package Marking and Ordering Information

| Device Marking | Marking Device Reel Size Tape width | | Tape width | Quantity |
|----------------|-------------------------------------|----|------------|------------|
| SS | BSS138-F085 | 7" | 8mm | 3000 units |

Electrical Characteristics

Symbol

Parameter

 $T_A = 25^{\circ}C$ unless otherwise noted

Test Conditions

Min

Max

Тур

Unit

| Off Ch | aracteristics | | | | | |
|-------------------|---|---|----|----|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, \qquad I_D = 250 \mu\text{A}$ | 50 | | | V |
| ΔBVDSS / ΔTJ | Breakdown Voltage Temperature Coefficient | I _D = 250 μA, Referenced to 25°C | | 72 | | mV/°C |
| | | V _{DS} = 50V, V _{GS} = 0 V | | | 0.5 | μΑ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 50V$, $V_{GS} = 0 V$, $T_{J} = 125$ °C | | | 5 | μΑ |
| | | V _{DS} = 30V, V _{GS} = 0 V | | | 100 | nA |
| I _{GSS} | Gate-Body Leakage | $V_{GS} = \pm 20V$, $V_{DS} = 0 V$ | | | ±100 | nA |

On Characteristics (Note2)

| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}$ | I _D = 1 mA | 8.0 | 1.3 | 1.5 | V |
|-------------------------------|---|--|----------------------------------|------|-----|-----|-------|
| ΔV _{GS(th)} / ΔTJ | Gate Threshold Voltage Temperature Coefficient | I _D = 1 mA, Refe | renced to 25°C | | -2 | | mV/°C |
| | | V _{GS} = 10 V, | I _D = 0.22 A | | 0.7 | 3.5 | |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 4.5 V, | I _D = 0.22 A | | 1.0 | 6.0 | Ω |
| | | V _{GS} = 10 V, I _D = | = 0.22 A, T _J = 125°C | | 1.1 | 5.8 | |
| I _{D(on)} | On-State Drain Current | V _{GS} = 10 V, | $V_{DS} = 5 V$ | 0.2 | | | Α |
| 9 _{FS} | Forward Transconductance | V _{DS} = 10 V, | I _D = 0.22 A | 0.12 | 0.5 | | S |

Dynamic Characteristics

| C _{iss} | Input Capacitance | V _{DS} = 25 V, f = 1.0 MHz | ., | | 27 13 | pF |
|------------------|------------------------------|--|------------------|--|----------|----|
| C _{oss} | Output Capacitance | | $V_{GS} = 0 V$, | | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | | 6 | pF |
| R _G | Gate Resistance | V _{GS} = 15 mV, | f = 1.0 MHz | | 9 | Ω |

Switching Characteristics (Note2)

| | | <u> </u> | | | | | |
|---------------------|---------------------|---|----------------------|---|----|------|----|
| $t_{d(on)}$ | Turn-On Delay Time | | | 2 | .8 | 5.8 | ns |
| t _r | Turn-On Rise Time | V _{DD} = 30 V, | $I_D = 0.29 A,$ | 2 | .1 | 4.4 | ns |
| t _{d(off)} | Turn-Off Delay Time | V _{GS} = 10 V, | $R_{GEN} = 6 \Omega$ | 9 | .6 | 19.2 | ns |
| t _f | Turn-Off Fall Time | | | 8 | .4 | 16.8 | ns |
| Qg | Total Gate Charge | | | 1 | .7 | 2.4 | nC |
| Q _{gs} | Gate-Source Charge | V _{DS} = 25 V, V _{GS} = 10 V | $I_D = 0.22 A,$ | 0 | .1 | | nC |
| Q_{qd} | Gate-Drain Charge | •GS 10 1 | | 0 | .4 | | nC |

Drain-Source Diode Characteristics and Maximum Ratings

| Is | Maximum Continuous Drain–Source Diode Forward Current | | | | | 0.22 | Α |
|-----|---|------------------------|-------------------------|----------|-----|------|---|
| VsD | Drain–Source Diode Forward Voltage | V _{GS} = 0 V, | I _S = 0.44 A | (Note 2) | 0.8 | 1.4 | V |

Notes

1. R_{NJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{NJC} is guaranteed by design while R_{NJA} is determined by the user's board design.



a) 350°C/W when mounted on a minimum pad.

Scale 1: 1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

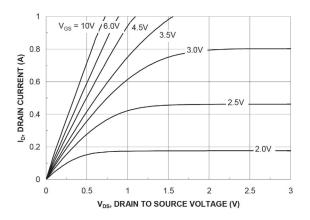


Figure 3. On-Resistance Variation with Temperature

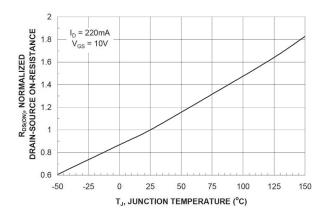


Figure 5. Transfer Characteristics

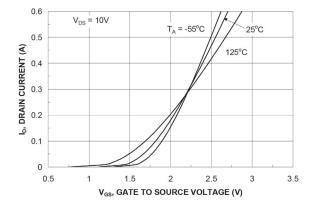


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

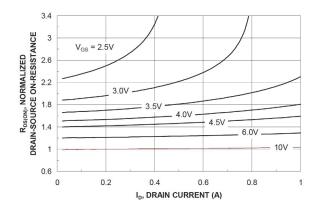


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

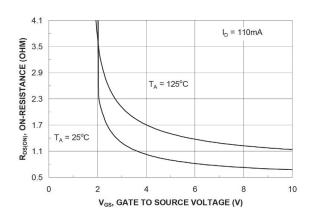
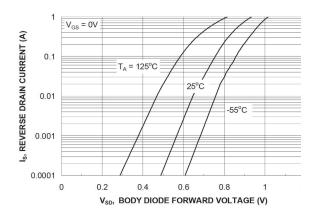


Figure 5. Body Diode Forward Voltage Variation with Source Current and Temperature



Typical Performance Characteristics

Figure 7. Gate Charge Characteristics

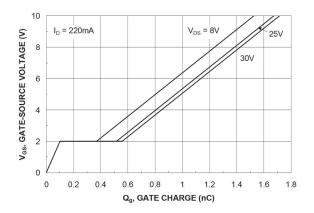


Figure 8. Capacitance Characteristics

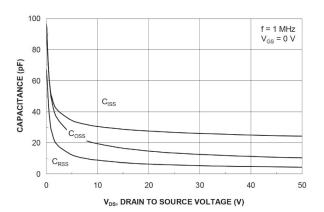


Figure 9. Maximum Safe Operating Area

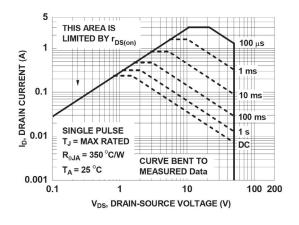


Figure 10. Single Pulse Maximum Power Dissipation

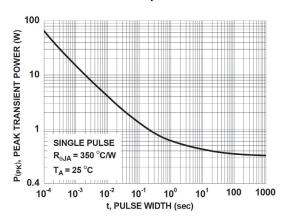
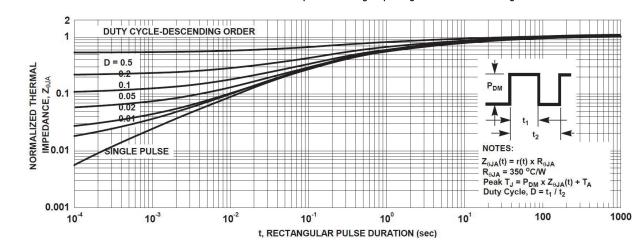


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1a Transient thermal response will change depending on the circuit board design



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